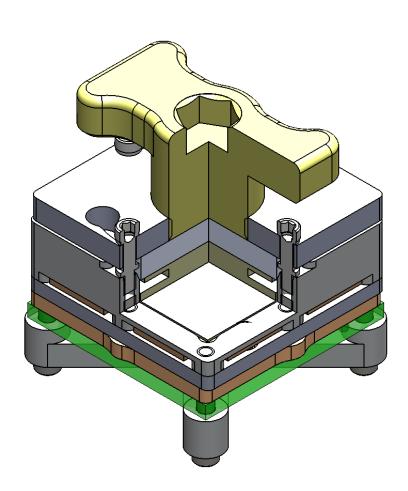
SBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS 23.2875 23.0750 **DETAIL G SCALE 16:1** 20.58 13.35 5.52

Features

- Wide temperature range (-55C to +180C)
 High current capability (up to 4A)
 Excellent signal integrity at high frequencies
 Low and stable contact resistance for reliable production yield
 Highly compliant to accommodate wide co-planarity variations
 Automated probe manufacturing enables low cost and short lead time



Description: SBT-BGA625 17x17mm, 0.65mm pitch 25x25 array

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

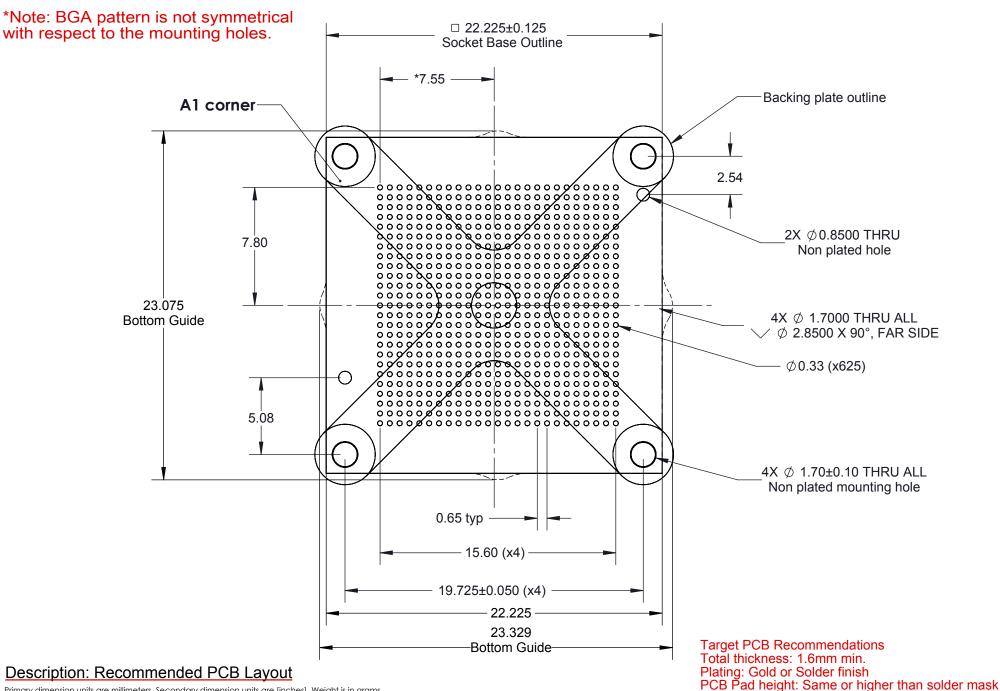
<u>Iolerances:</u> Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change SBT-BGA-7008 Drawing

	OD
7.7	

Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodélectronics.com Material: Material <not specified> Finish:

Weight: 18.15

STATUS: Released	SHEET: 1 OF 5	REV. B
ENG: V. Panavala	DRAWN BY: V. Panavala	SCALE: 3:1
FILE: SBT-BGA-7008 Dwg	DATE: 2/20/2013	



Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

<u>Iolerances:</u> Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change

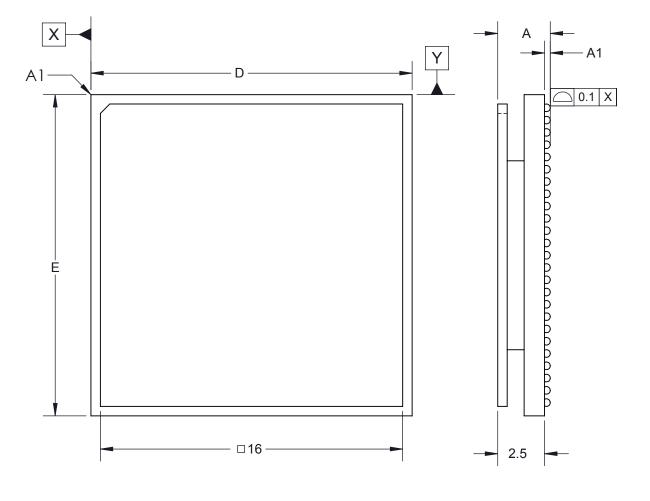
SBT-BGA-7008 Drawing

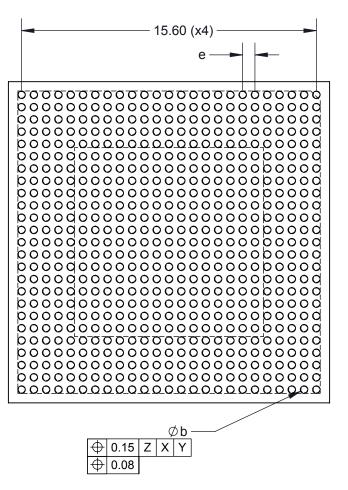
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Material: Material <not specified> Finish:

Weight: 18.15

SHEET: 2 OF 5 REV. B STATUS: Released DRAWN BY: V. Panavala SCALE: 4:1 ENG: V. Panavala FILE: SBT-BGA-7008 Dwg DATE: 2/20/2013





Ironwood Package Code: BGA625D

- Dimensions are in millimeters.
- 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	Minimum	Maximum
Α		3.2
A1	0.25	0.35
b	0.35	0.45
D	17.0 BSC	
E	17.0 BSC	
е	0.65 BSC	

25x25 array

Description: Compatible BGA

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

 $\underline{\textbf{Iolerances:}} \ \ \textbf{Hole diameters \pm 0.0254mm [\pm 0.001"], Pitches (from true position) \pm 0.0762mm [\pm 0.003"], substrate thickness tolerance \\ \underline{\pm 10\%, \text{ oil other tolerances \pm 0.127mm [\pm 0.005"] unless stated otherwise.} \ \ \textbf{Materials and specifications are subject to change without the state of the state o$

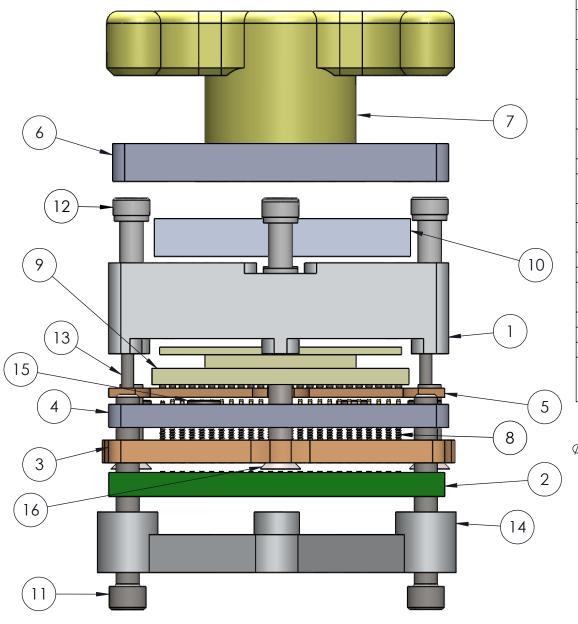
SBT-BGA-7008	Drawing
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Weight: 18.15

STATUS: Released	SHEET: 3 OF 5	REV. B
ENG: V. Panavala	DRAWN BY: V. Panavala	SCALE: 5:1
FILE: SBT-BGA-7008 Dwg	DATE: 2/20/2013	



ITEM NO.	DESCRIPTION	Material	
1	Socket Base, SBT BGA, 17x17mm 0.25mm shift	7075-T6 Aluminum Alloy	
2	PCB 17x17mm, 0.65mm pitch 25x25 array	High Temp FR4	
3	Bottom Guide	Semitron MDS 100	
4	Middle Guide	Semitron MDS 100	
5	Floating Guide	Semitron MDS 100	
6	Socket Lid Swivel 11mm IC	7075-T6 Aluminum Alloy	
7	Compression Screw M10 w/handle	7075-T6 Aluminum Alloy	
8	SBT Pin, SBT-BGA 0.5mm-0.8mm		
9	BGA625 IC 17x17mm, 0.65mm pitch 25x25 array	High Temp FR4	
10	Compression Plate	7075-T6 Aluminum Alloy	
11	#0-80 x 0.5, SH Cap Screw	Alloy Steel	
12	#0-80 Shoulder Screw, 0.062" thread length	Stainless Steel (303)	
13	Dowel pin, 1/32" X 1/4", SS	Stainless Steel (18-8)	
14	Backing Plate 17mm SBT	7075-T6 Aluminum Alloy	
15	Floating Guide Spring	Alloy Steel (SS)	
16	#0-80, 90 deg., head pin guide screw, Peek material 5.5715mm overall Length	PEEK unfilled	

Backing Plate Specification Scale 2:1 Ø 1.70 THRU- \emptyset 4 (x4) □ 19.725

Description: Socket Assy, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SBT-BGA-7008	Drawing
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Material: Material <not specified> Finish:

Weight: 18.15

STATUS: Released	SHEET: 4 OF 5	REV. B
ENG: V. Panavala	DRAWN BY: V. Panavala	SCALE: 4:1
FILE: SBT-BGA-7008 Dwg	DATE: 2/20/2013	

Rev	Date	Initials	Description
Α	02/20/13	VP	Original
В	01/30/15	DH	Updated layout page
С	2/19/15	RP/MR	Changes to Guides per MP237 and MP238, P-P196A was P-P149A, R3200 was R2885, adjusted dowel pins

Description: REVISIONS

Primary dimension units are millimeters, Secondary dimension units are [inches], Weight is in grams.

Tolerances: Hole diameters ±0.0254mm [±0.001"], Pitches (from true position) ±0.0762mm [±0.003"], substrate thickness tolerance ±10%, all other tolerances ±0.127mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

SB	T-BGA-7008 Drawing
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STATUS: Released	SHEET: 5 OF 5	REV. B
ENG: V. Panavala	DRAWN BY: V. Panavala	SCALE: 4:1
FILE: SBT-BGA-7008 Dwg	DATE: 2/20/2013	